



Material Content Data Sheet



Sales Product Name		SPD30P06P G		Issued		27. September 2017		
MA#		MA000444030						
Package		PG-TO252-3-311		Weight*		316.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.913	1.24	1.24	12384	12384
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.27	45.33	452812	453401
wire	non noble metal	aluminium	7429-90-5	9.947	3.15	3.15	31474	31474
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.858	0.59		5878	
	plastics	brominated resin	-	1.990	0.63		6298	
	organic material	carbon black	1333-86-4	2.123	0.67		6718	
	plastics	epoxy resin	-	17.912	5.67		56680	
	inorganic material	silicondioxide	60676-86-0	108.799	34.43	41.99	344278	419852
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11983	11983
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275
solder	noble metal	silver	7440-22-4	0.078	0.02		247	
	non noble metal	tin	7440-31-5	0.062	0.02		197	
	non noble metal	lead	7439-92-1	2.978	0.94	0.98	9424	9868
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60684	60763
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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